



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

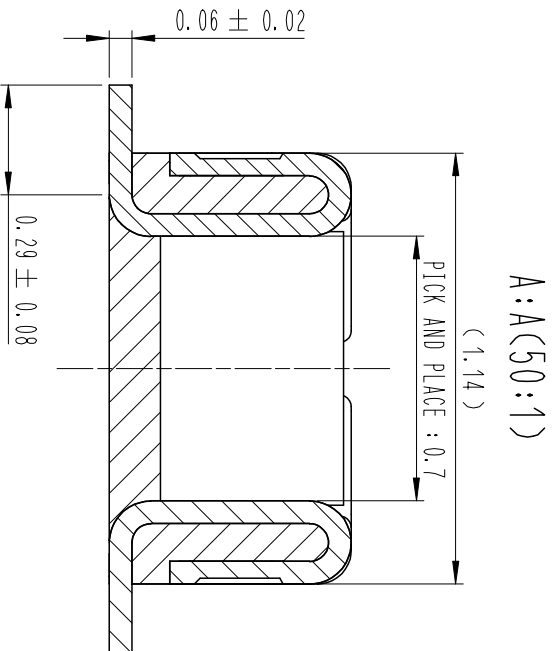
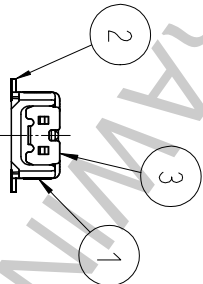
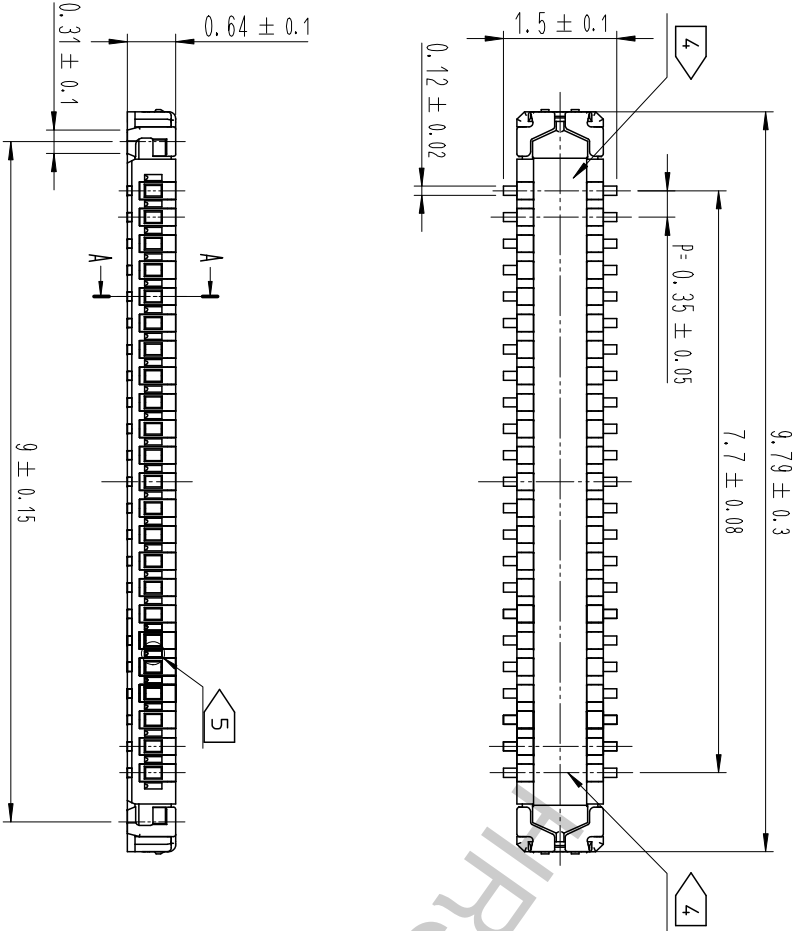
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

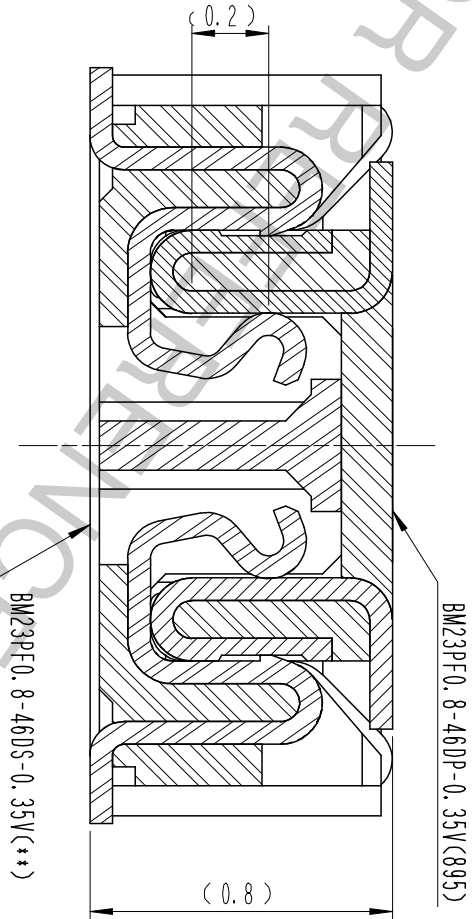


訂正事項				訂正事項			
△數	DESCRIPTION OF REVISIONS	擔當檢圖	年月日	△數	DESCRIPTION OF REVISIONS	擔當檢圖	年月日
COUNT		B Y	CHKD DATE	COUNT		B Y	CHKD DATE
△			..	△			..
△			..	△			..
△			..	△			..



ENGAGEMENT FIGURE (50:1)

DRAWING FOR REFERENCE
This is subject to change without notice

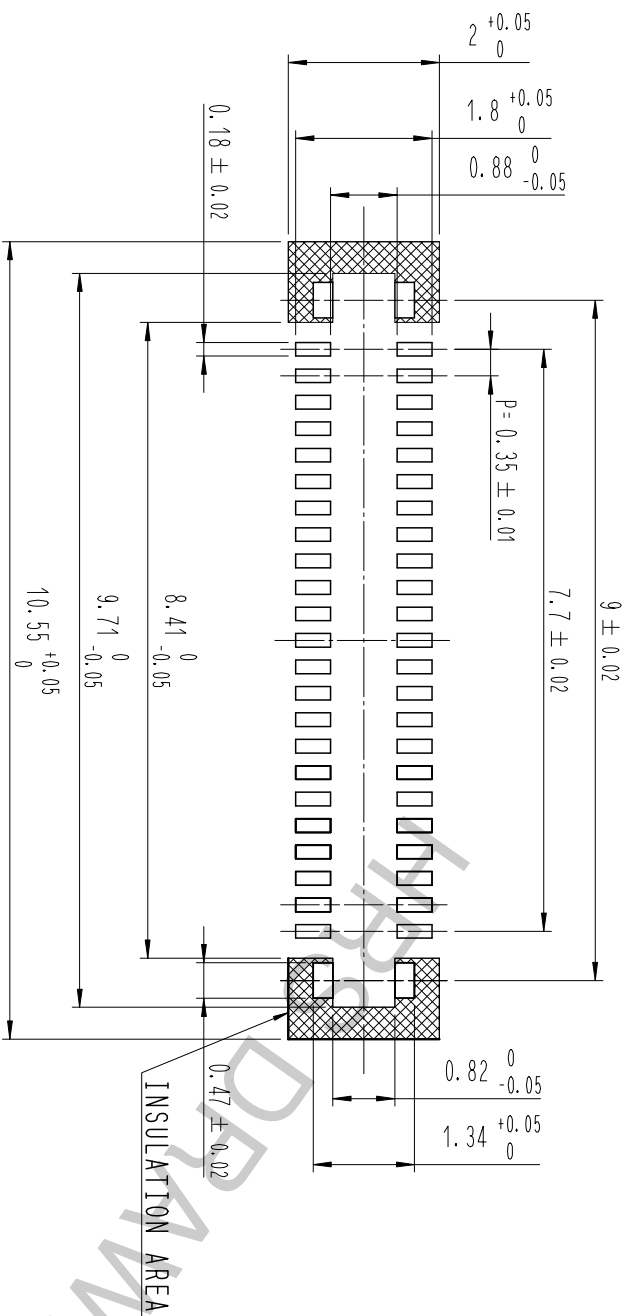


NOTE 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.

2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDER PLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
5. A PART OF THE WALL COULD BE NOTCHED.

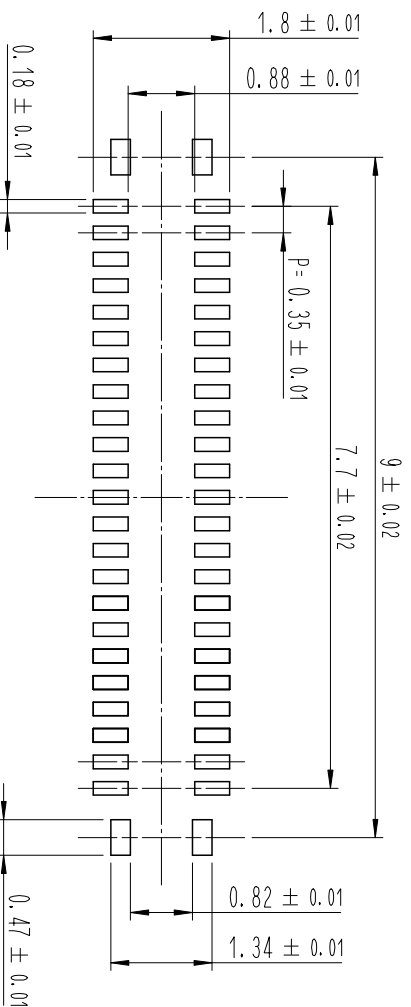
4	PS	CLEAR (EMBOSSED CARRIER TAPE)						
3	COPPER ALLOY	3						
2	COPPER ALLOY	2						
1	LCP	UL94 V-0, BLACK		5	PS	BLACK (PLASTIC REEL)		
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS			
REMARKS								
			DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED	
			S. H. JUNG	S. H. JUNG	H. W. JO	T. S. KANG	17. 05. 09	
			17. 05. 09	17. 05. 09	17. 05. 09	17. 05. 09		
CODE NO. (OLD)			DRAWING NO.			PART NO.		
			EDC3-632257			BM23PF0. 8-46DP-0. 35V(895)		
			HRS HIROSE KOREA CO., LTD.			CODE NO		
						CL 6644-0088-5-895		
						1 / 3		

 RECOMMENDED PCB LAYOUT

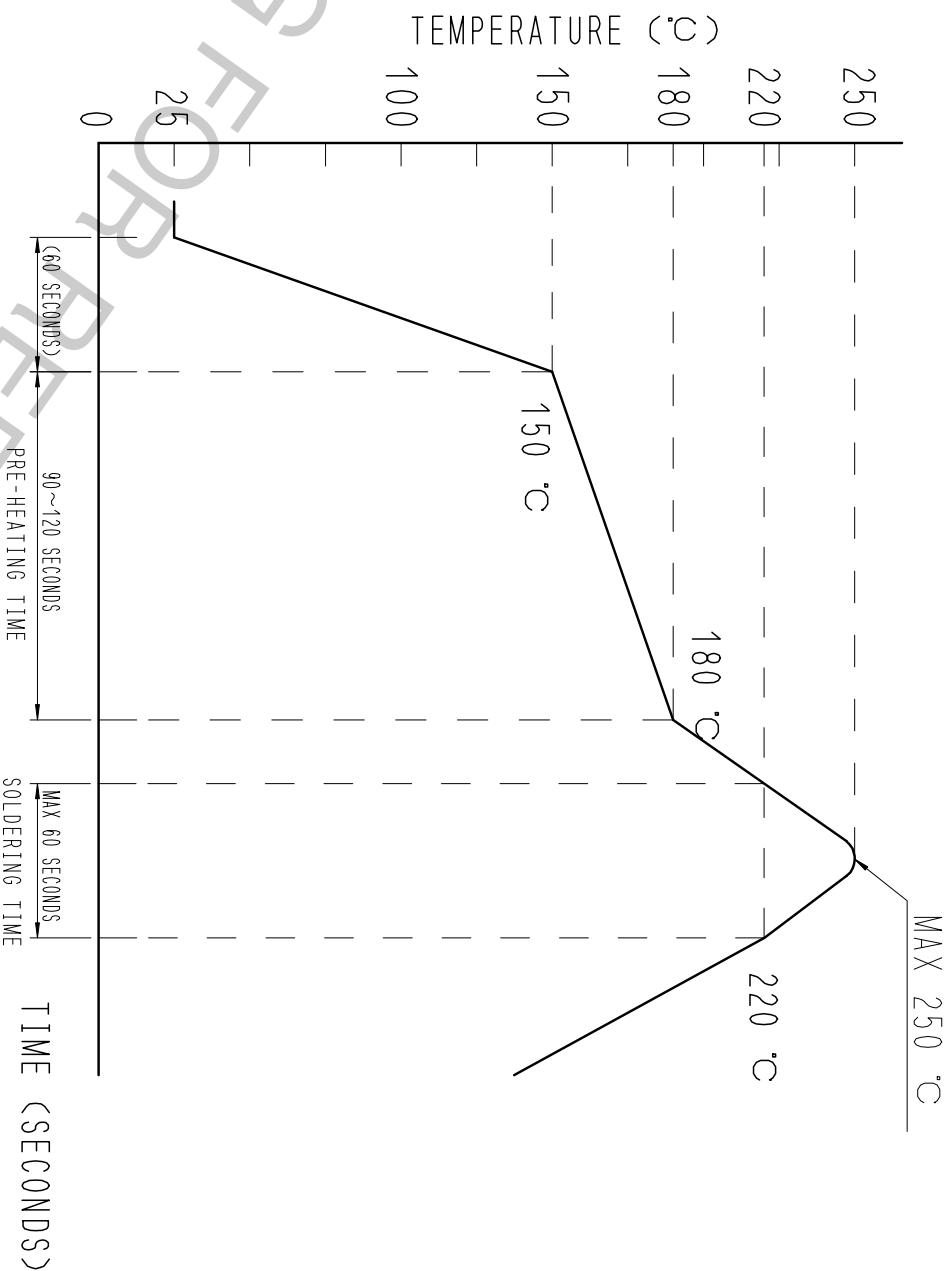


RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μ m



6 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.







REFLOW METHOD: N2 REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)

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2)PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN):150°C
PRE-HEAT TEMPERATURE(MAX):180°C
PRE-HEAT TIME: 90-120 SEC.
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6. THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.

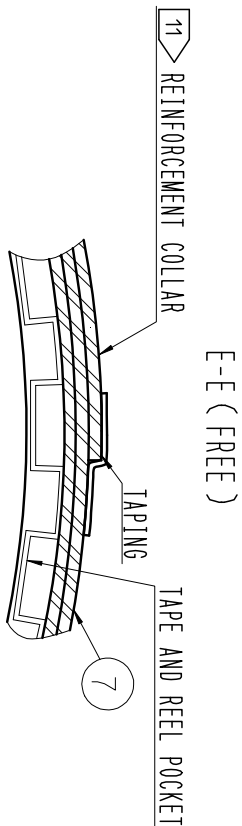
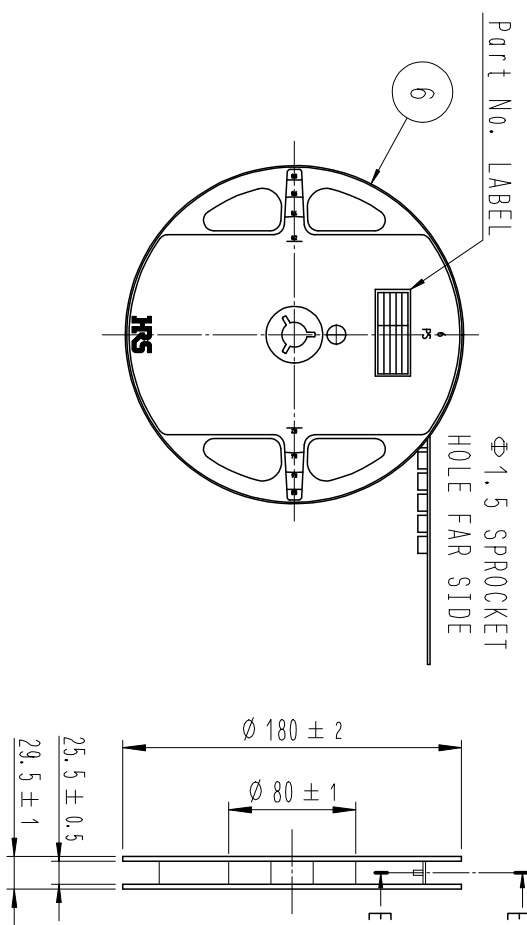
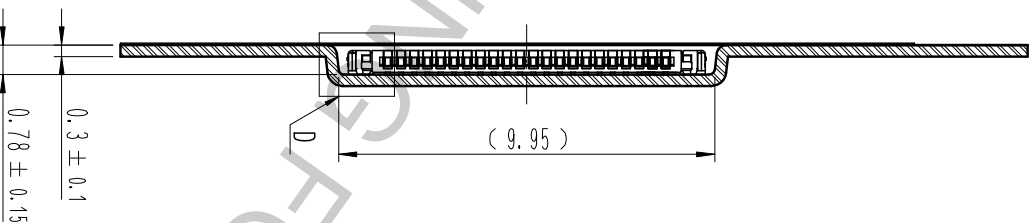
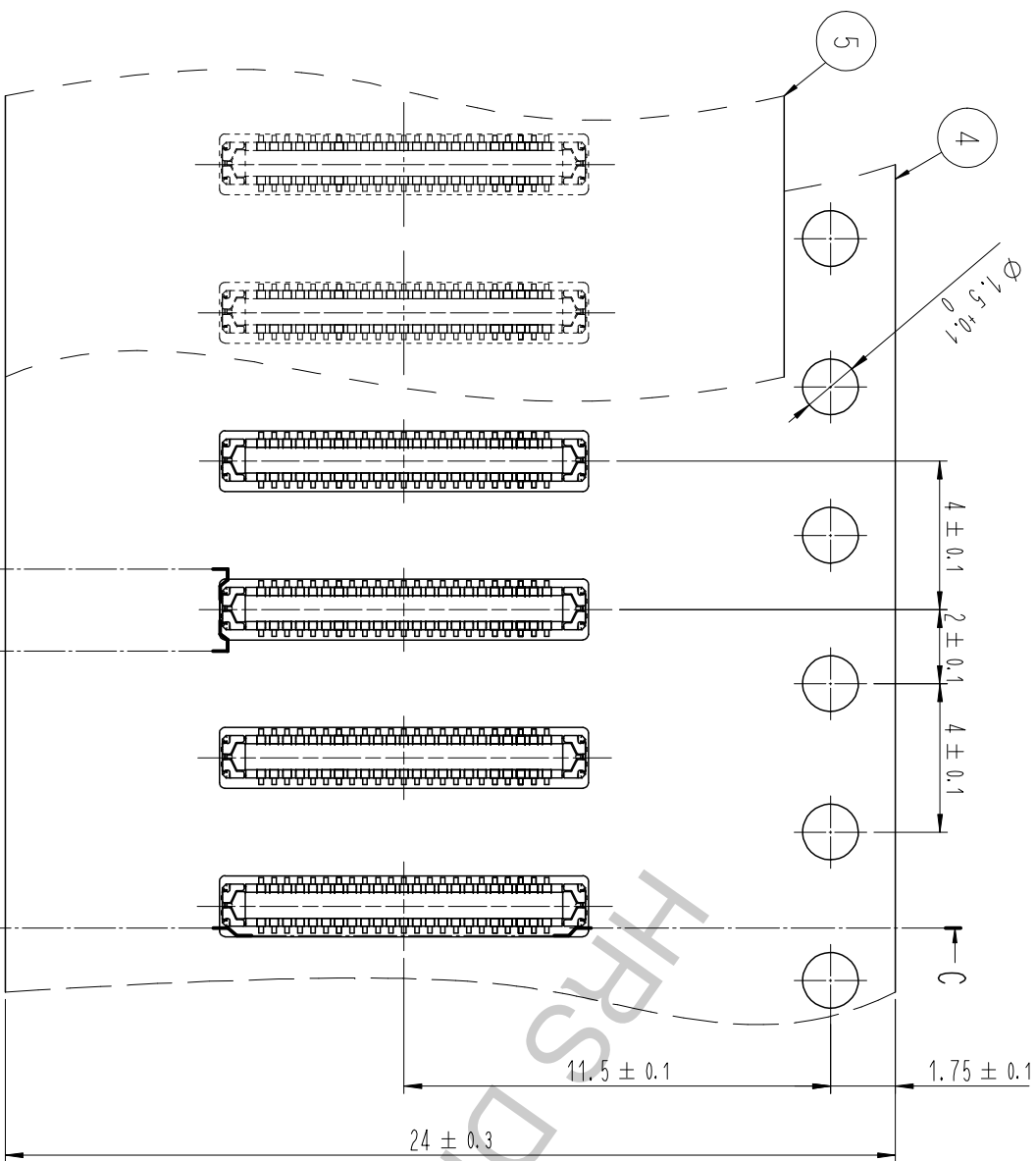
6. THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-632257	PART NO.	BM23PFO.8-46DP-0.35V(895)
	SCALE	10:1	CODE NO	CL 6644-0088-5-895
	UNITS	mm	<div style="display: flex; justify-content: space-between; align-items: center;"> <div>  HIROSE KOREA CO., LTD. </div> <div style="border: 1px solid black; padding: 2px;"> <div style="display: flex; justify-content: space-between;"> 2 3 </div> </div> </div>	

EMBOSSED CARRIER TAPE PACKAGING (5:1)

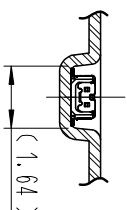
C-C (5:1)

STYLE AND DIMENTION OF REEL (FREE)

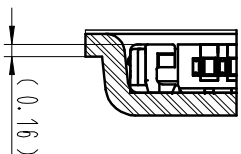


B-B (5:1)

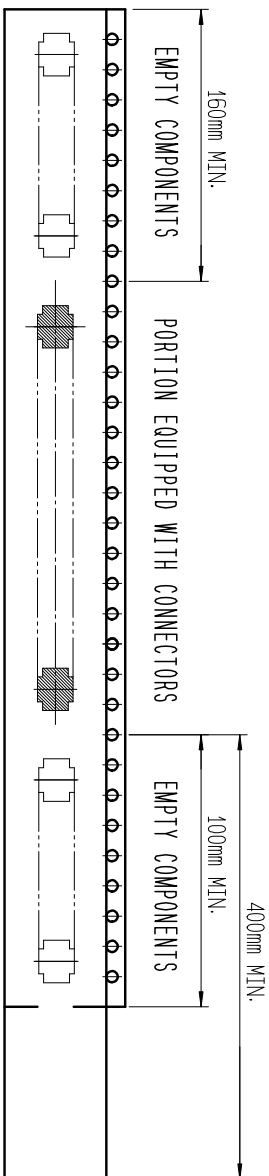
DIRECTION OF UNREELING



D (10:1)



10 TAPING(FREE)



- 8 . PER REEL 1,000 CONNECTORS.
9 . THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.
10 REFER TO JIS C 0806, IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
11 AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

DETAIL OF PART NO. LABEL

SUPPLIER		DATE OF MANUFACTURED	
PART NO.	CODE NO.	生産月日	年 月 日
図番	品名	納入数量	納入者
BM23PF0.8-46DP-0.35V(895)	1,000個	HIROSE KOREA	

DRAWING NO.		PART NO.	
SCALE	10:1	CODE NO	3
UNITS	mm		
EDC3-632257		BM23PF0.8-46DP-0.35V(895)	
HIROSE KOREA CO., LTD.		CL 6644-0088-5-895	